

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In Re Patent Application: An-Chun Tu *et al.*

Serial Number: 10/700,779

Filed: 11/04/2003

Title: METHOD FOR IMPROVING  
INTERLEVEL DIELECTRIC GAP  
FILLING OVER SEMICONDUCTOR  
STRUCTURES HAVING HIGH ASPECT  
RATIOS

: Group Art Unit: 2818

: Examiner: David Nhu

: Attn. Docket No.: TS03-268

: Date: July 13, 2004

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Commissioner for Patents  
P.O. Box 1450  
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**AMENDMENT AND RESPONSE**

Dear Sir:

This paper is responsive to the Office action dated May 26, 2004. Kindly enter the following amendments and remarks:



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PHONE: 609.919.4400  
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## FACSIMILE TRANSMITTAL SHEET

**TO:** Art Unit 2818

**FIRM/COMPANY:** USPTO

**FACSIMILE NUMBER:** 703-872-9306

**CONFIRMATION  
TELEPHONE:**

**FROM:** Won Joon Kouh

**DIRECT DIAL:** 609.919.4435

**DATE:** July 13, 2004

**USER NUMBER:** 3927

**FILE NUMBER:** USSN: 10/700,779

**TOTAL # OF PAGES:  
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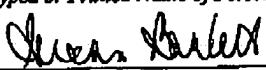
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<b>CERTIFICATE OF TRANSMISSION BY FACSIMILE (37 CFR 1.8)</b>				Docket No. TS03-268
Applicant(s): An-Chun Tu et al.				
Application No. 10/700,779	Filing Date 11/4/2003	Examiner David Nhu	Group Art Unit 2818	
Invention: <b>METHOD FOR IMPROVING INTERLEVEL DIELECTRIC GAP FILLING OVER SEMICONDUCTOR STRUCTURES HAVING HIGH ASPECT RATIOS</b>				
<p>I hereby certify that this <u>Amendment and cover sheet</u> (Identify type of correspondence)</p> <p>is being facsimile transmitted to the United States Patent and Trademark Office (Fax. No. <u>703-872-9306</u></p> <p>on <u>7/13/2004</u> (Date)</p> <p><u>Susan Barlett</u> (Typed or Printed Name of Person Signing Certificate)  (Signature)</p>				
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<b>AMENDMENT TRANSMITTAL LETTER (Large Entity)</b>					Docket No. <b>TS03-268</b>	
Applicant(s): An-Chun Tu et al.						
Application No. <b>10/700,779</b>	Filing Date <b>11/4/2003</b>	Examiner <b>David Nhu</b>	Customer No. <b>28581</b>	Group Art Unit <b>2818</b>	Confirmation No. <b>5490</b>	
<b>Invention: METHOD FOR IMPROVING INTERLEVEL DIELECTRIC GAP FILLING OVER SEMICONDUCTOR STRUCTURES HAVING HIGH ASPECT RATIOS</b>						
<b><u>COMMISSIONER FOR PATENTS:</u></b>						
Transmitted herewith is an amendment in the above-identified application.						
The fee has been calculated and is transmitted as shown below.						
<b>CLAIMS AS AMENDED</b>						
	CLAIMS REMAINING <b>AFTER AMENDMENT</b>	HIGHEST # <b>PREV. PAID FOR</b>	NUMBER EXTRA <b>CLAIMS PRESENT</b>	RATE	ADDITIONAL FEE	
TOTAL CLAIMS	26	26 =	0	x \$18.00	\$0.00	
INDEP. CLAIMS	2	3 =	0	x \$86.00	\$0.00	
Multiple Dependent Claims (check if applicable) <input type="checkbox"/>					\$0.00	
<b>TOTAL ADDITIONAL FEE FOR THIS AMENDMENT</b>					\$0.00	
<p><input checked="" type="checkbox"/> No additional fee is required for amendment.</p> <p><input type="checkbox"/> Please charge Deposit Account No. _____ in the amount of _____</p> <p><input type="checkbox"/> A check in the amount of _____ to cover the filing fee is enclosed.</p> <p><input checked="" type="checkbox"/> The Director is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Deposit Account No. 50-2061</p> <p><input type="checkbox"/> Any additional filing fees required under 37 C.F.R. 1.16.</p> <p><input type="checkbox"/> Any patent application processing fees under 37 CFR 1.17.</p>						
 <i>Signature</i>						
Dated: 7/13/2004						
<div style="border: 1px solid black; padding: 10px; width: fit-content; margin: auto;"> <p>I certify that this document and fee is being deposited on _____ with the U.S. Postal Service as first class mail under 37 C.F.R. 1.8 and is addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.</p> </div>						
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